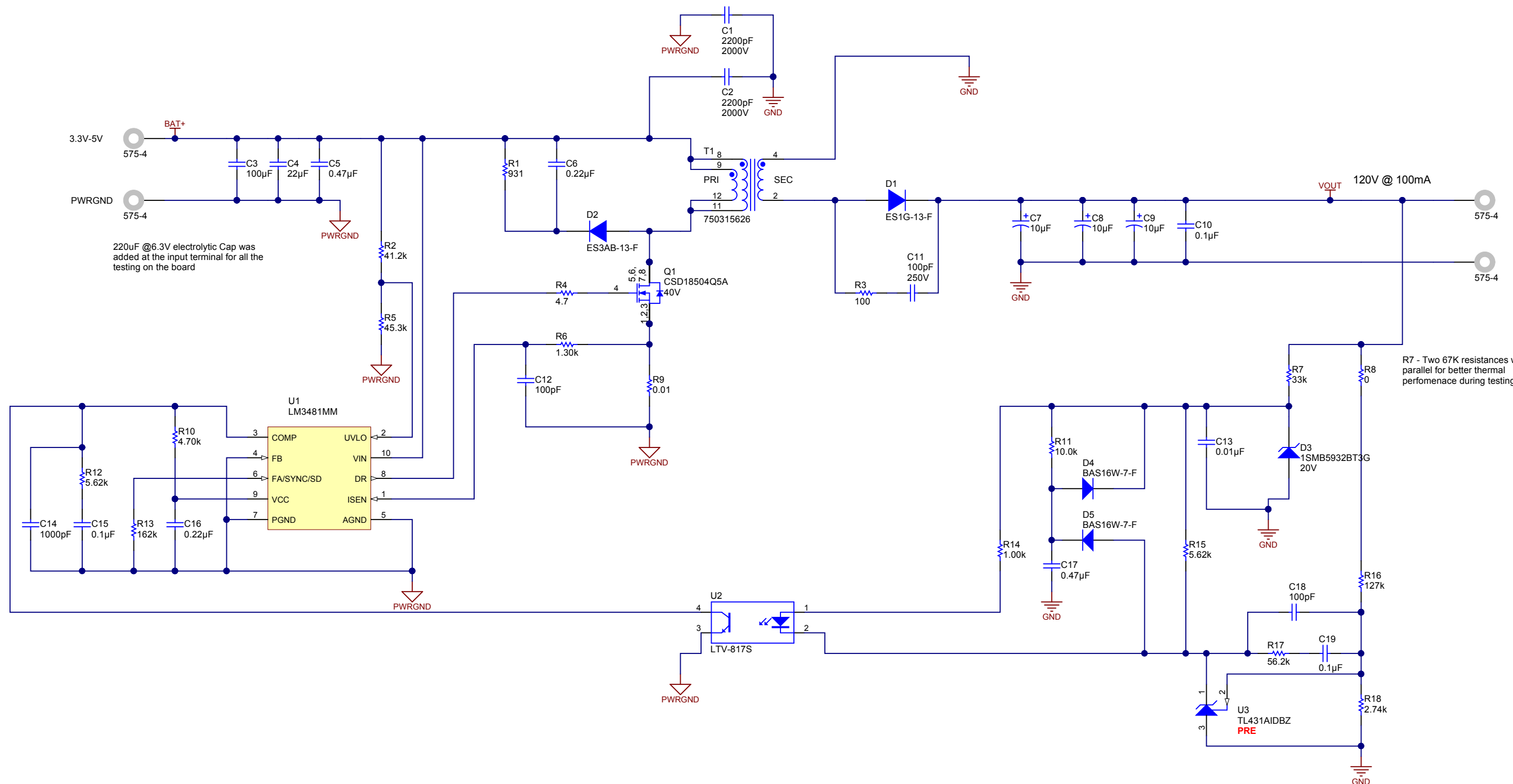


XFRMR detils :

Primary - Secondary Ration 4-2:8-12 =1:15
 Primary Peak Current = 8.5A
 Primary RMS current = 4.3A
 Secondary Peak Current= 0.560
 Secondary RMS= 0.170
 Primary Inductance=1.5uH
 EE16 Core (N87/CF139)



220µF @6.3V electrolytic Cap was added at the input terminal for all the testing on the board

R7 - Two 67K resistances were put in parallel for better thermal performence during testing

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Number: PMP10666	Rev: E1	Designed for: Public Release	Mod. Date: 8/12/2015
SVN Rev: Not in version control	Assembly Variant: 001	Project Title: Low VIN FLYback design for Avalanche Photo Diode	Sheet Title:
Drawn By:	File: PMP10666_Sch REV1_SchDoc	Sheet: 1 of 1	Size: B
Engineer: Ambresh Tripathi	Contact: http://www.ti.com/support		



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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

DNP FID1 DNP FID2 DNP FID3

PCB Number: PMP10666
PCB Rev: E1

PCB LOGO
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PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
PMP10666

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: PMP10666	Rev: E1	Designed for: Public Release	Mod. Date: 6/24/2015
SVN Rev: Not in version control	Assembly Variant: 001	Project Title: Low VIn FLYback design for Avalanche Photo Diode	Sheet Title:
Drawn By:	File: PMP10666_Hardware_SchDoc	Sheet: 1 of 1	Size: B
Engineer: Ambresh Tripathi	Contact: http://www.ti.com/support	 http://www.ti.com © Texas Instruments 2015	

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